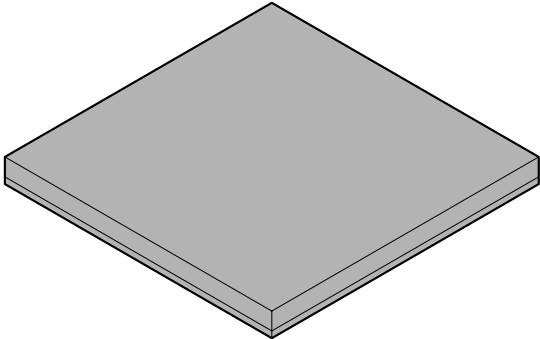
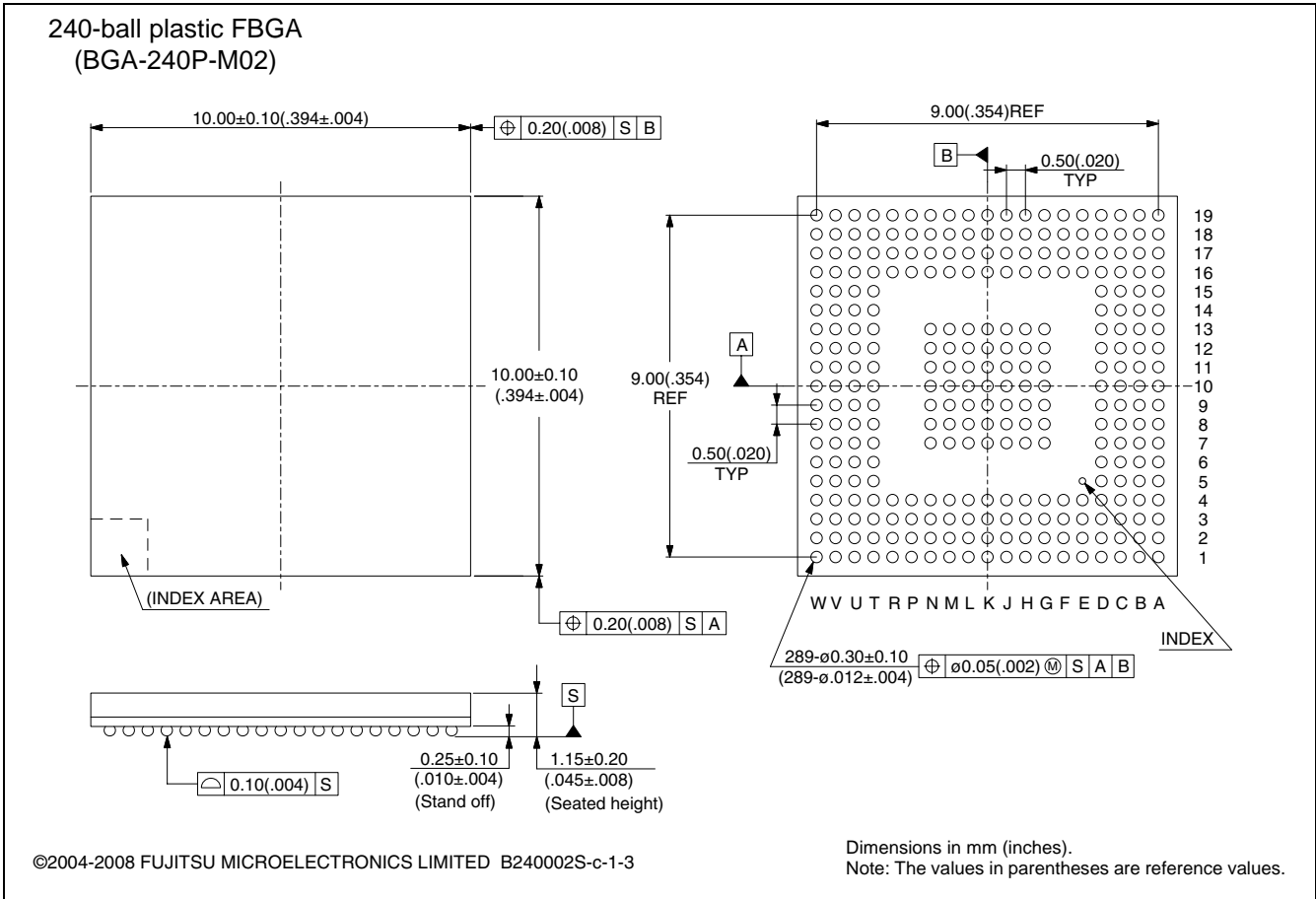


BGA-240P-M02

<p>240-ball plastic FBGA</p>  <p>(BGA-240P-M02)</p>	Ball pitch	0.500 mm
	Package width × package length	10.00 × 10.00 mm
	Lead shape	Soldering ball
	Sealing method	Plastic mold
	Ball size	∅0.30 mm
	Mounting height	1.35 mm Max
	Weight	0.24 g



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